US00D888000S

(12) **United States Design Patent**
Lim

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(54) **CASE FOR A CIRCUIT BOARD**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/184**
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USPC D13/182, 184, 199; D3/201, 272, 273, D3/274, 303; D10/21, 46, 24, 25, 104.1; D9/414, 432
CPC H05K 1/00; H05K 5/00; H05K 5/0004; H05K 5/0008; H05K 5/0091; H05K 5/03; H05K 5/04; H05K 7/20; H05K 7/00; H05K 7/005
See application file for complete search history.

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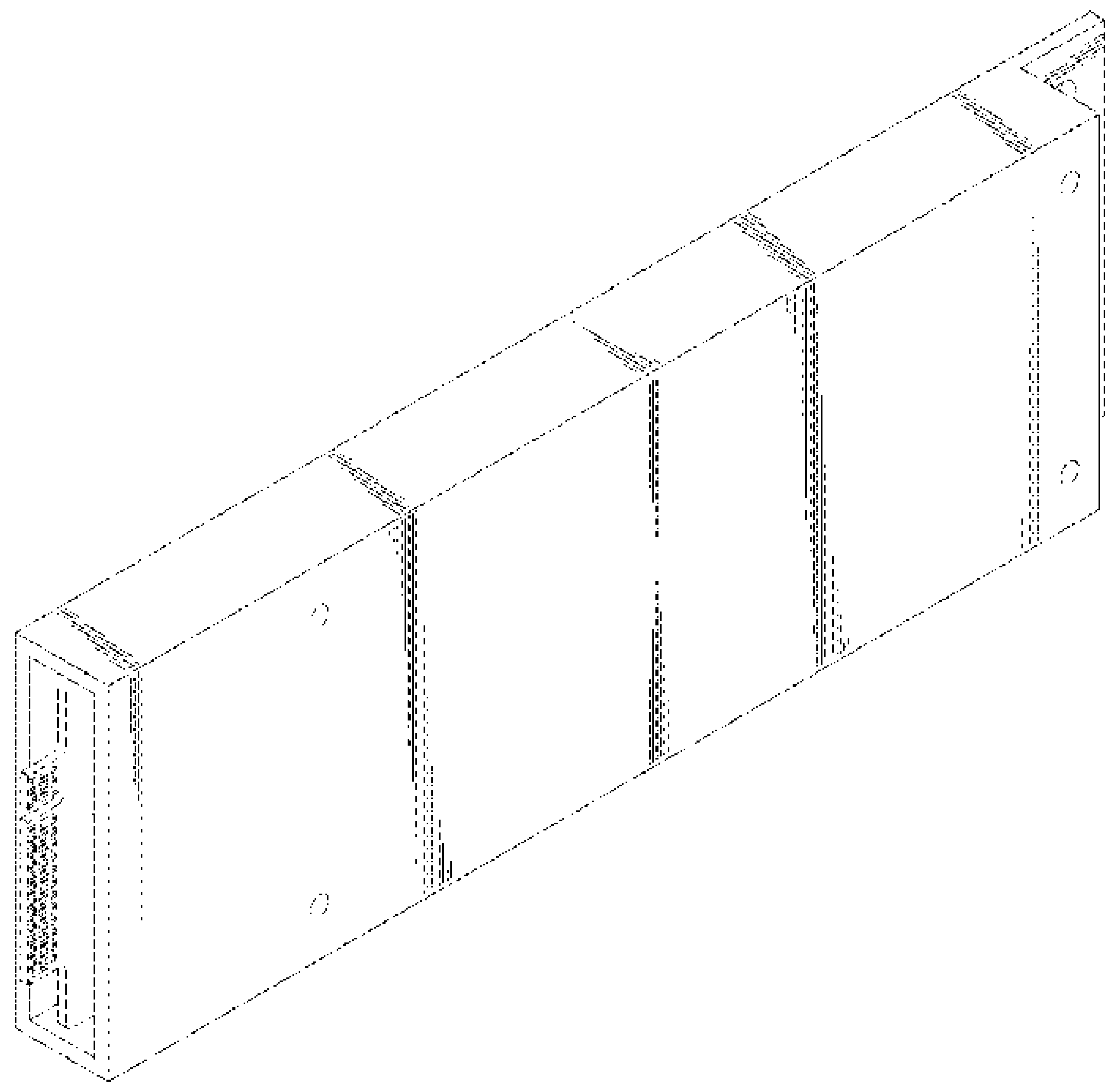
(57) **CLAIM**

The ornamental design for a case for a circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a case for a circuit board showing our new design;
FIG. **2** is a front elevation view thereof;
FIG. **3** is a rear elevation view thereof;
FIG. **4** is a left side elevation view thereof;
FIG. **5** is a right side elevation view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof; and,
FIG. **8** is a perspective view of a case for a circuit board shown in a used condition with a circuit board shown in broken lines.
The broken lines are for environmental purposes only and form no part of the claimed design.

1 Claim, 5 Drawing Sheets



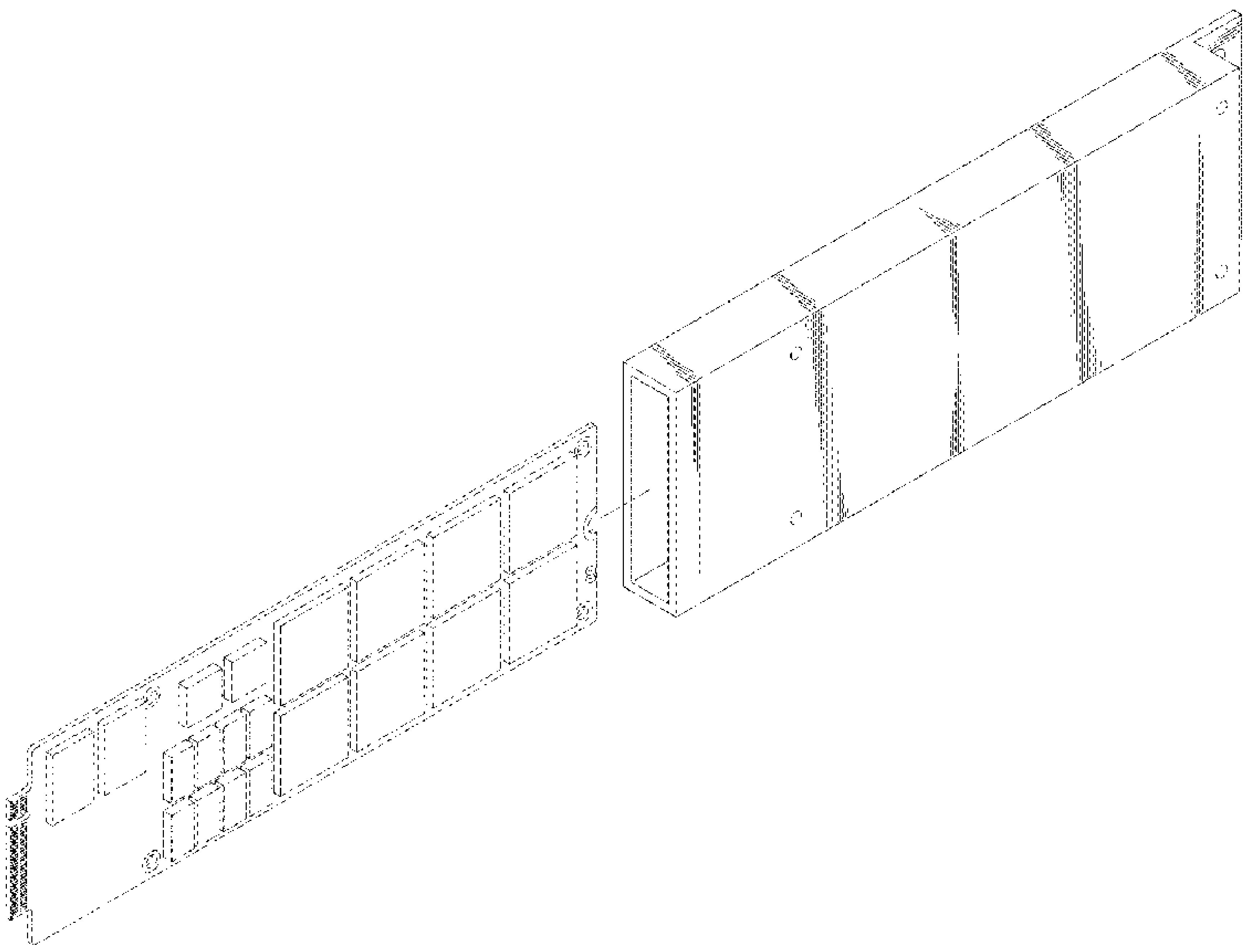


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FIG. 1

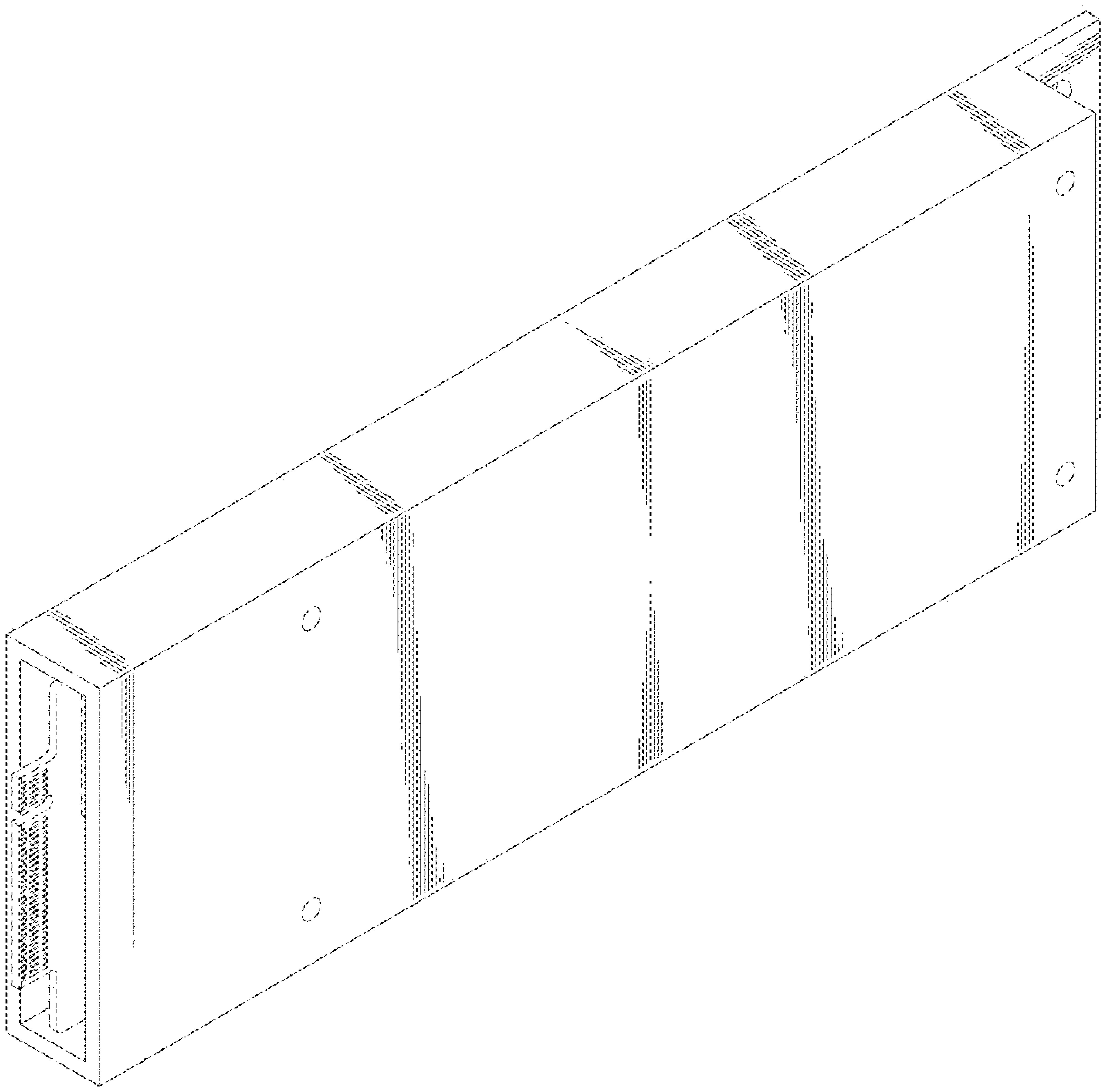

FIG. 2

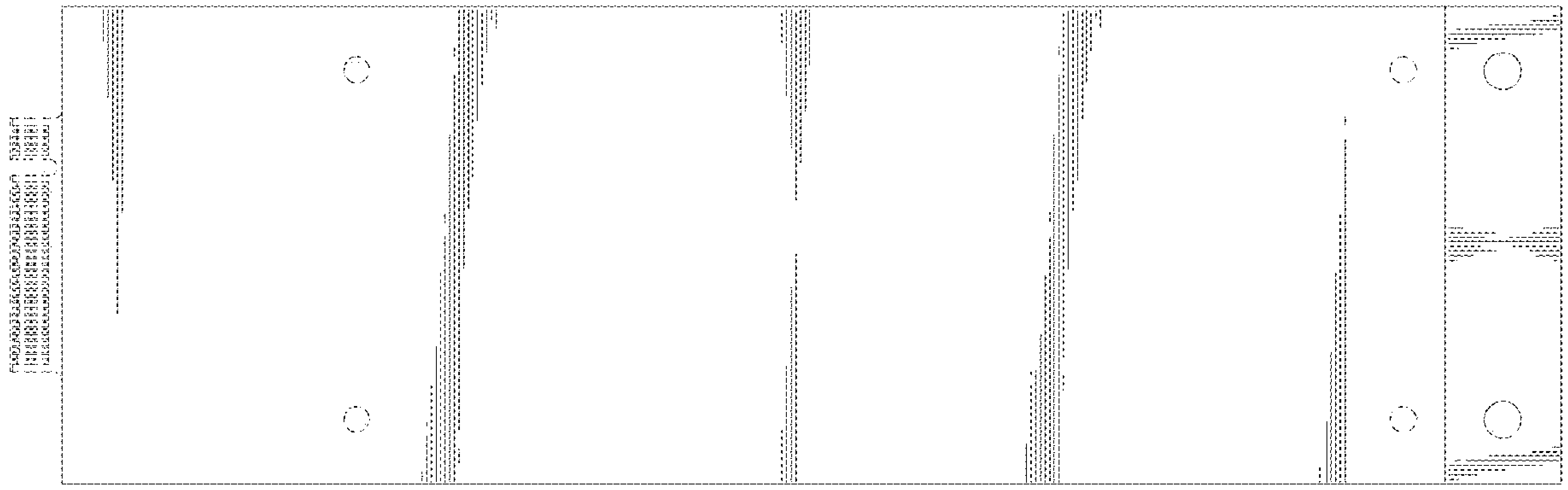

FIG. 3

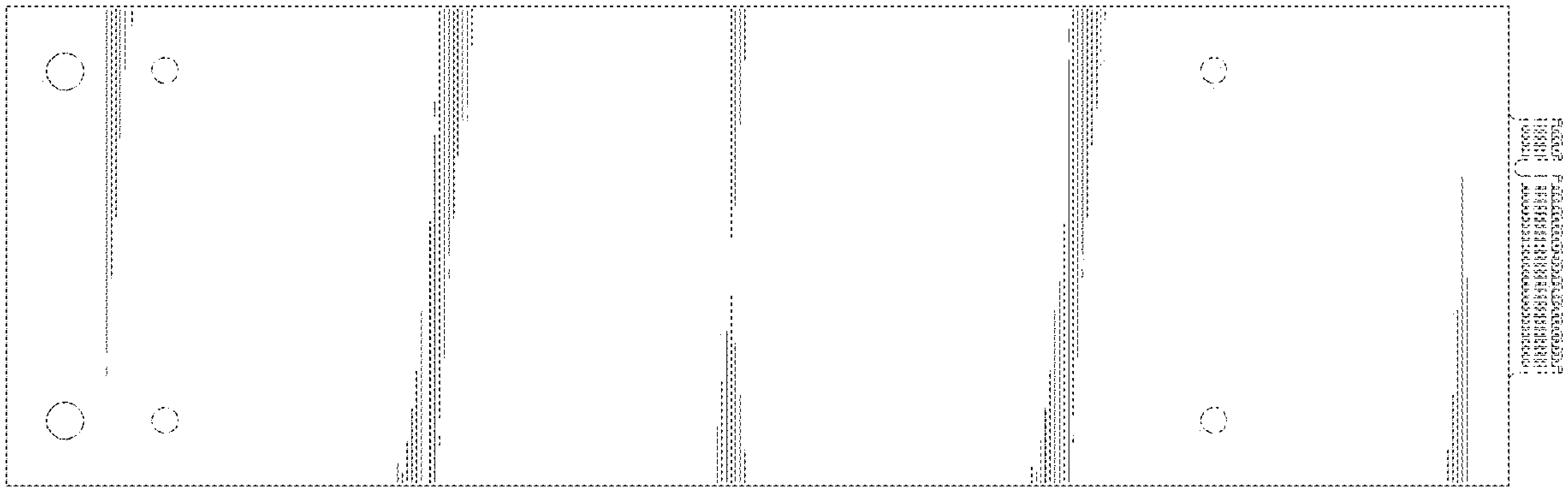

FIG. 4

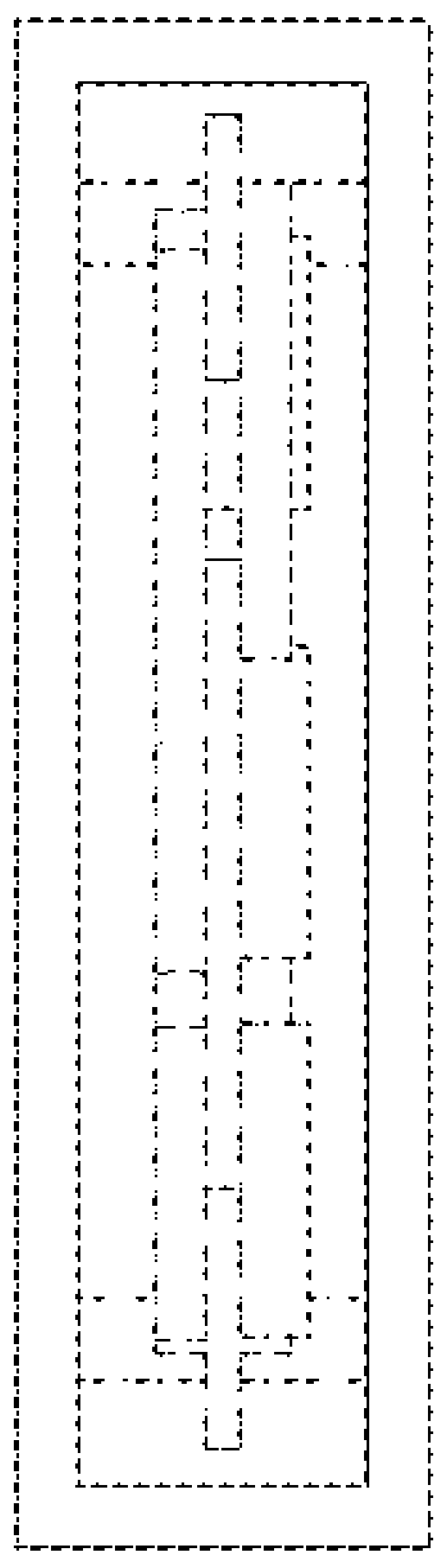

FIG. 5

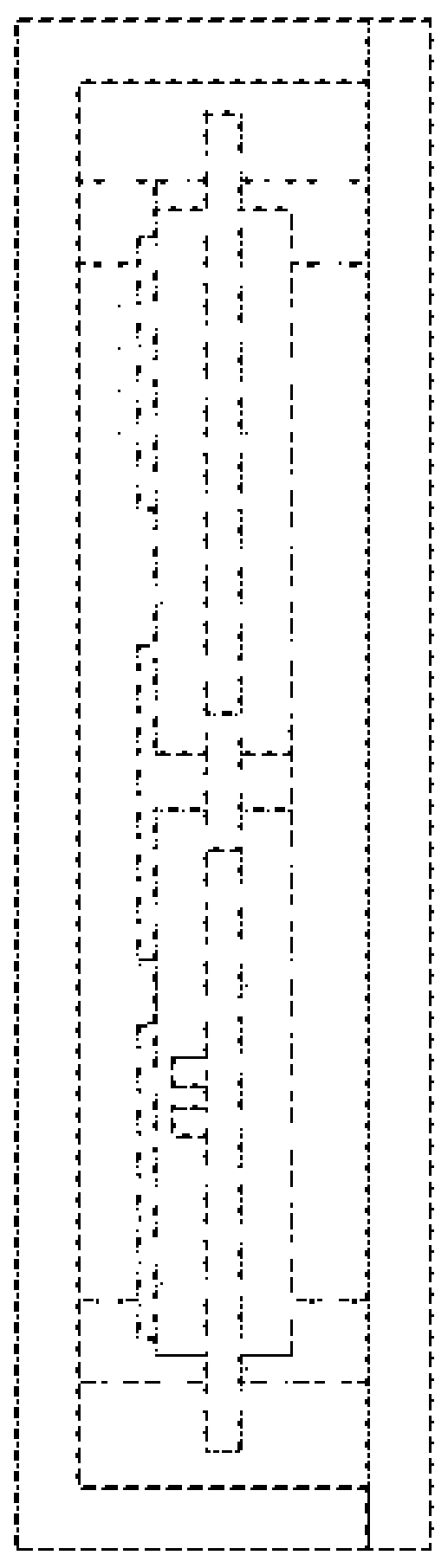

FIG. 6

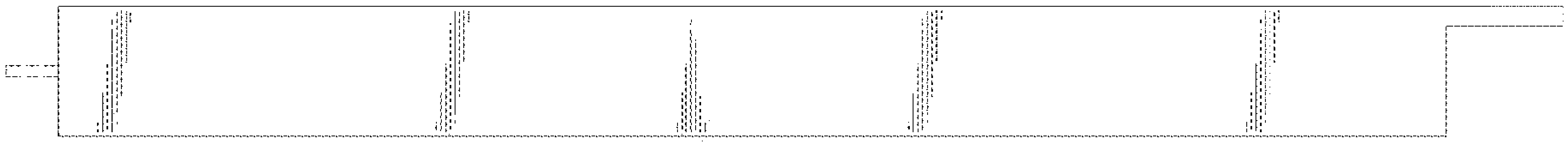

FIG. 7

FIG. 8